SHEET

101056570 To the Honorable Commissioner of Pa. ached original documents or copy thereof Name of conveying party(ies): Mikio NISHIO and Tomoyasu MURAKAMI Additional name(s) of conveying party(ies) attached? Yes X No JUN 2 Name and address of receiving party(ies): Matsushita Electronics Corporation Street Address: 1-1, Saiwai-cho, Takatsuki-shi ZIP 569-1193 Osaka State Japan Additional name(s) & addresses(es) attached? ___ Yes __X_ No 6.2-99 Name of Conveyance: X Assignment Merger ___ Security Agreement Change of Name Other __ Execution Date: May 6, 1999 Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: ___ Title: A: Patent Application No. 09/285,647 B. Patent No.(s) Additional numbers attached? __ Yes _X No Name and address of party to whom correspondence concerning document should be mailed: Sixbey, Friedman, Leedom & Ferguson, P.C. Street Address: 8180 Greensboro Drive, Suite 800 ZIP City: McLean State: Virginia Total number of applications and patents involved: 1 6. Total fee (37 CFR 3.41):\$40.00 7. X Enclosed Authorized to be charged to deposit account X Authorized to charge any deficiency in the payment of the required fee(s) or credit any overpayment to Deposit Account No. 19-2380. Deposit Account Number: 19-2380 (Attach duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE 06/04/1999 HTHAI1 00000192 09285647 Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Eric J. Robinson Name of Person Signing Total number of pages comprising cover sheet, attachments and document: 3

> PATENT REEL: 009995 FRAME: 0556

SIXBEY, FRIEDMAN, LEEDOM & FERGUSON, P.C. United States Patent Rights

Attorney	Docket	No	

ASSIGNMENT

WHEREAS, Mikio NISHIO, Tomoyasu MURAKAMI	
(hereinafter designated as the undersigned) has (have) invented certain new and use	ful
improvements in POLISHING PAD FOR SEMICONDUCTOR WAFER AND METHO)D
FOR POLISHING SEMICONDUCTOR WAFER	
for which an application for Letters Patent of the United States of America has been executed	by
the undersigned on May 6, 1999, and;	-
WHEREAS, Matsushita Electronics Corporation	of
1-1, Saiwai-cho, Takatsuki-shi, Osaka 569-1193, Japan	
its heirs, successors, legal representatives and assigns (hereinafter designated as the Assigne	<u></u> эе)
is desirous of acquiring the entire right, title and interest in and to said invention and in and	to
any Letters Patent(s) that may be granted therefor in the United States of America;	

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

PATENT REEL: 009995 FRAME: 0557 The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby convenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Sixbey, Friedman, Leedom & Ferguson, P.C. the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

In witness thereof, this Assignment has been executed by the undersigned on the date(s) opposite the undersigned name(s).

Date M	ay 6, 1999	_, Name of Inventor Mikio NISHIO	Z (SEAL)
Date	ay 6, 1999	_, Name of Inventor <u>Jomoyasu Murakan</u> Tombyasu MURAKAMI	12 (SEAL)
Date		_, Name of Inventor	(SEAL)
Date		_, Name of Inventor	(SEAL)
Date		_, Name of Inventor	(SEAL)
or Notar	y Public. If not	should preferably be acknowledged before a United State to the the execution by the Inventor(s) should be so who should sign here.)	tates Consul witnessed by
Witness	Yasuhito KUM	MABUCHI Yasutu Kuhahu (signature)	<u>. Jui</u>
Witness	Tatsuya MIYA (name)	AZATO Zatauja Jnigaj (signatuje)	2 <i>5</i>

PATENT REEL: 009995 FRAME: 0558

RECORDED: 06/02/1999